

SOT948-1

plastic thermal enhanced ball grid array package; 1092 balls;
body 40 x 40 x 1.75 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA1092
Package type industry code	HBGA1092
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	31-5-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	39.8	-	40	40.2	mm
E	package width	39.8	-	40	40.2	mm
A	seated height	[tbd]	-	2.45	2.45	mm
A ₂	package height	1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination	-	-	1092	-	

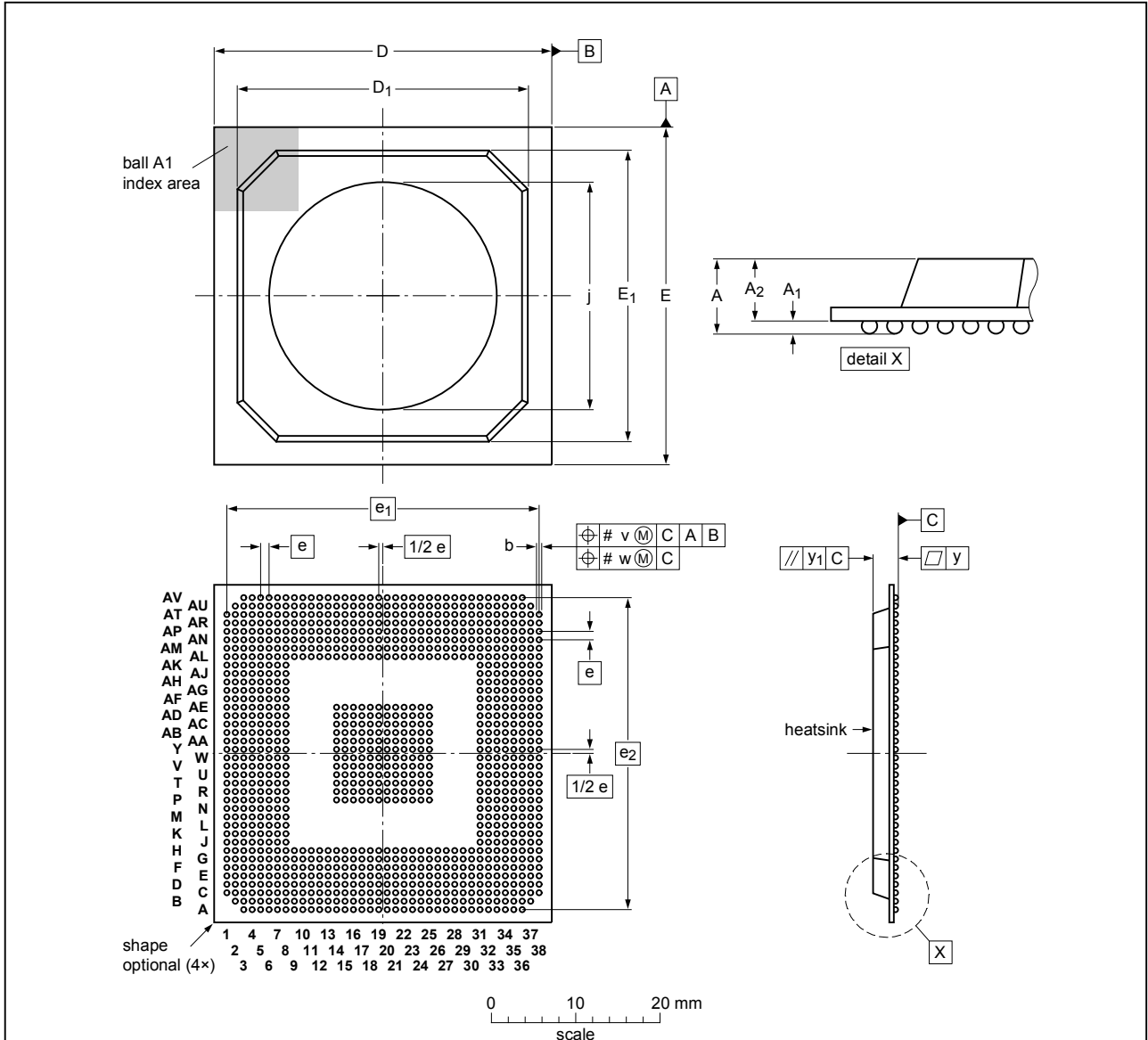


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2. Package outline

HBGA1092: plastic thermal enhanced ball grid array package; 1092 balls;
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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	e ₂	j	v	w	y	y ₁
mm	2.45	0.6 0.4	1.85 1.60	0.7 0.5	40.2 39.8	35.25 34.25	40.2 39.8	35.25 34.25	1	37	37	30 26	0.25	0.1	0.2	0.35

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT948-1	144E	MS-034			05-07-13 06-05-31

Fig. 1. Package outline HBGA1092 (SOT948-1)

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3. Legal information

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